

DS3174DK DS3/E3 Single-Chip Transceiver Demo Kit

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GENERAL DESCRIPTION

The DS3174DK is an easy-to-use demo kit for the DS3174. A surface-mounted DS3174 and careful layout of the analog signal traces provide maximum signal integrity to demonstrate the transmit and receive capabilities of the DS3174. On-board Dallas 8051-compatible microcontroller and included software give point-and-click access to configuration and status registers from a personal computer. General-purpose LEDs on the board can easily be configured to indicate various alarm conditions for all four ports. The board provides eight BNC connectors for the line-side transmit and receive differential pairs, and two FPGAs to support overhead functions. All LEDs and connectors are clearly labeled with silkscreening to identify associated signals.

DEMO KIT CONTENTS

DS3174DK Board CD-ROM

> ChipView Software DS3174 Definition Files DS3174DK Data Sheet DS3174 Data Sheet

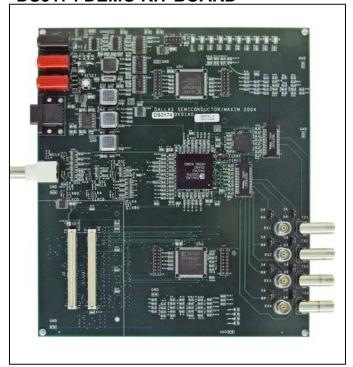
ORDERING INFORMATION

PART	DESCRIPTION
DS3174DK	Demo Kit for the DS3174

FEATURES

- Soldered DS3174 for Best Signal Integrity
- BNC Connectors, Transformers, and Termination Passives for All Four LIUs
- Careful Layout for Analog Signal Paths
- On-Board DS3, E3, and STS-1 Crystal Oscillators
- DS3174 Configured for CPU Bus Operation for Complete Control Over the Device
- On-Board Dallas Microcontroller and Included Software Provide Point-and-Click Access to the DS3174 Register Set
- General-Purpose LEDs can be Configured for Various Alarm Conditions
- Banana Jack Connectors for V_{DD} and GND Support Use of Lab Power Supplies
- Separate DS3174 V_{DD} to Allow I_{DD} Measurements
- Easy-to-Read Silkscreen Labels Identify the Signals Associated with All Connectors, Jumpers, and LEDs

DS3174 DEMO KIT BOARD



1 of 23 REV: 060106

COMPONENT LIST

DESIGNATION QT		DESCRIPTION	MANUFACTURER	PART	
C1, C2, C12, C13, C14, C18, C19, C44, C54, C57, C65, C69, C70, C74, C75	15	10μF ±20%, 10V ceramic capacitors (1206)	Panasonic	ECJ-3YB1A106M	
C3–C7, C9, C10, C11, C20, C21, C24–C38, C46, C47, C58–C64, C66, C67, C68, C76–C87, C95, C98, C100, C102, C109–C137	82	0.1μF ±20%, 16V X7R ceramic capacitors	AVX	0603YC104MAT	
C8, C15, C39, C40	4	4.7μF ±10%, 25V X5R ceramic capacitors	Panasonic	ECJ-3YB1E475K	
C16, C17, C41, C42			Panasonic	ECJ-3YB0J685K	
C22, C23	2	22pF ±5%, 25V NPO ceramic capacitors	AVX	06033A220JAT	
C43, C103	2	68μF ±20%, 16V tantalum capacitors (D case)	Panasonic	ECS-T1CD686R	
D1 1		Diode, 1A, 50V, general-purpose silicon	General Semiconductor	1N4001	
DS1, DS10	2	Green SMD LEDs	Panasonic	LN1351C	
C43, C103 2 D1 1 DS1, DS10 2 DS2-DS9 8 DS21 1 J1, J4 2 J2, J3 2 J5 1 J6, J8, J10, J12 4		Red SMD LEDs	Panasonic	LN1251C	
C22, C23 2 C43, C103 2 D1 1 DS1, DS10 2 DS2-DS9 8 DS21 1 J1, J4 2 J2, J3 2 J5 1		Red SMD LED	Panasonic	LN1251C	
C3-C7, C9, C10, C11, C20, C21, C24-C38, C46, C47, C58-C64, C66, C67, C68, C76-C87, C95, C98, C100, C102, C109-C137 C8, C15, C39, C40 C16, C17, C41, C42 C22, C23 C43, C103 D1 DS1, DS10 DS2-DS9 DS21 J1, J4 J2, J3 J5 J1 J6, J8, J10, J12 J7, J9, J11, J13 J14 J15-J18 J1 J15-J18 J1 J25 JMP1, JMP2, JMP15 JMP15 JMP3-JMP6, JMP17, JMP16, JMP17, JMP18, JMP23-JMP26 JMP7-JMP10, JMP2 JMP7-JMP10, JMP7, JMP18, JMP26 JMP7-JMP10, JMP17, JMP18, JMP23-JMP26 JMP7-JMP10, JMP17, JMP19-JMP20 R1, R2, R3, R16-R19, R36-R39, R36-R39,		Sockets, banana plug, horizontal, red	Mouser (distributor)	164-6219	
J2, J3	2	Plugs, SMD, 140-pin, 0.8mm, 2-row vertical	AMP	179031-6	
J5	1	Socket, banana plug, horizontal, black	Mouser (distributor)	164-6218	
J6, J8, J10, J12	4	BNC connectors 75Ω, vertical, 5-pin	Cambridge	CP-BNCPC-004	
J7, J9, J11, J13	4	Connector, BNC, 75 ohm, right angle, 5-pin	Trompeter	UCBJR220	
J14	1	Amphenol, right-angle BNC	Amphenol	31-5431	
J15–J18	4	Terminal strip, 16-pin, dual-row, vertical	Samtec	TSW-108-07-T-D	
J21	1	Connector, DB9, right-angle, long case	AMP	747459-1	
J25	1	Terminal strip, 10-pin, dual-row, vertical	_	_	
C66, C67, C68, C76–C87, C95, C98, C100, C102, C109–C137 C8, C15, C39, C40 4 C16, C17, C41, C42 4 C22, C23 2 C43, C103 2 D1 1 DS1, DS10 2 DS2–DS9 8 DS21 1 J1, J4 2 J2, J3 2 J5 1 J6, J8, J10, J12 4 J7, J9, J11, J13 4 J14 1 J15–J18 4 J21 1 J25 1 JMP1, JMP2, JMP15 JMP1, JMP2, JMP15 JMP3–JMP6, JMP17, JMP16, JMP17, JMP18, JMP23–JMP26 JMP7–JMP10, JMP22 R1, R2, R3, R16–R19, R36–R39, R41–R51, R53–R59, R61–R68, R229–R231, R244 R4, R146, R147, R148, R158, R159, R160 R5, R8–15, R92, R93, R95, R161, R95, R61-R69, R93, R95, R161, R57, R95, R93, R95, R161, R57, R93, R95, R161, R57, R95, R95, R161, R57, R93, R95, R161, R57, R95, R95, R95, R95, R95, R95, R95, R95		2-pin header, 0.100 centers, vertical	Samtec	TSW-102-07-T-S	
JMP3-JMP6, JMP11-JMP14, JMP16, JMP17, JMP18, JMP23- JMP26	15	3-pin header, 0.100 centers, vertical	Samtec	TSW-103-07-T-S	
JMP3–JMP6, JMP11–JMP14, JMP16, JMP17, JMP18, JMP23– JMP26 JMP7–JMP10, JMP19–JMP22		Do not place, open 2 pin TH jumper	_	_	
R1, R2, R3, R16– R19, R36–R39, R41–R51, R53– R59, R61–R68, R229–R231, R244		0Ω ±1%, 1/16W resistors (0603)	AVX	CJ10-000F	
R148, R158, R159, R160	7	Resistors (0603) Do not populate	_	_	
R93, R95, R161, R270–R285, R313–	37	10kΩ \pm 5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ103V	

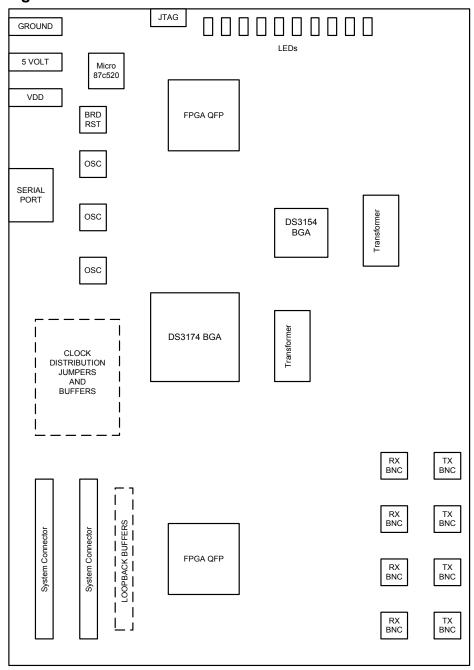
DESIGNATION	QTY	DESCRIPTION	MANUFACTURER	PART		
R6, R7, R28–R35, R77–R91, R94, R96–R145, R149– R157, R162–R228, R233–R240, R255– R266, R305–R312, R321–R329	189	33Ω ±5%, 1/16W resistors (0603) Panasonic EF		ERJ-3GEYJ330V		
R20-R27, R69-R76	16	$332\Omega \pm 1\%$, 1/16W resistors (0603)	Panasonic	ERJ-3EKF3320V		
R52, R246–R254	10	$330\Omega \pm 5\%$, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ331V		
R232	1	51.1Ω ±1%, 1/16W resistor (0603)	Panasonic	ERJ-3EKF51R1V		
R241	1	3.3kΩ ±5%, 1/16W resistor (0603)	Panasonic	ERJ-3GEYJ332V		
R242 R243 R245		4.7kΩ ±5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ472V		
R286-R304, R330	20	100Ω ±5%, 1/16W resistors (0603)	Panasonic	ERJ-3GEYJ101V		
SW5 1		Switch, momentary, 4-pin, single pole	Panasonic	EVQPAE04M		
T1, T2	2	Octal T3/E3 transformers, 1 to 2, SMD 32-pin	Pulse Engineering	T3049		
TP3-TP10, TP17, TP21-TP32, TP70	22	Test points, 1 plated hole, do not stuff	stuff — —			
U1	1	Quad DS3\E3 single-chip transceiver (400-pin CSBGA)	Dallas Semiconductor	DS3174		
U2	1	Quad DS3/E3/STS1 LIU (144-pin CSBGA)	Dallas Semiconductor	DS3154		
U3	1	Dual RS-232 transmitter/receiver (16-pin SO, 300 mils)	Dallas Semiconductor	DS232AS		
U4, U5, U6, U10, U11, U12 6		IC, 3.3V octal buffer/driver (20-pin narrow SOP)	Texas Instruments	SN74ALVC244NSR		
U11, U12 ⁶ U8 1		IC, 3-line to 8-line decoder/demultiplexer (16-pin SOIC)	Texas Instruments	SN74HC138NSR		
U9 1		Microprocessor voltage monitor, 3.08V reset (4-pin SOT143)	Maxim	MAX811TEUS-T		
U13 1		IC, TinyLogic ultra-high-speed 2-input exclusive-OR gate (5-pin SOT23)	Fairchild	NC7SZ86M5		
U14	1	Microprocessor voltage monitor, 4.38V reset (4-pin SOT143)	Maxim	MAX812MEUS-T		
U17 1		Microprocessor reset circuit, 3.08V reset (3-pin SC70)	Maxim	MAX803TEXR-T		
U18–U25, U41–U46 14		IC, TinyLogic ultra-high-speed 2-input OR gate (5-pin SOT23) Fairchild		NC7SZ32M5		
U26, U27, U29	3	3.3V linear regulator (16-pin TSSOP-EP)	Maxim	MAX1793EUE-33		
U28	1	IC, Xilinx platform flash in-system-programmable config PROM (20-pin TSSOP)	Xilinx	XCF04SVO20C		
U30	1	1.8V linear regulator (16-pin TSSOP-EP)	Maxim	MAX1793EUE-18		
U31	1	IC, hex inverter, SOIC	Toshiba	TC74HC04AFN		

DESIGNATION	QTY	DESCRIPTION MANUFACTU		PART
U32, U33, U34	3	IC, 5.0V octal buffer/driver (20-pin narrow SOIC) Texas Instruments		SN74HC244NSR
U40 1 High-speed microcontroller (44-pin TQFP) Dallas Semicon		Dallas Semiconductor	DS87C520-ECL	
U50, U51 2 IC, Xilinx Spartan 100k gate, 1.8V FP (144-pin TQFP)		IC, Xilinx Spartan 100k gate, 1.8V FPGA (144-pin TQFP)	Xilinx	XC2S100E-6TQ144C
Y1 1 11.0592MHz low-profi		11.0592MHz low-profile crystal	Pletronics	LP49-33-11.0592M
Y2 1 3.3V, 34.368MHz		3.3V, 34.368MHz oscillator	Saronix	NTH089AA3-34.368
Y4 1 3.		3.3V, 44.736MHz oscillator	Saronix	NTH089AA3-44.736
Y3	Y3 1 3.3V, 51.840MHz oscillator Saronix		Saronix	NTH089AA3-51.840

BOARD FLOOR PLAN

Figure 1 shows the floor plan of the DS3174DK. The DS3174 is near the center of the board. The analog circuitry is on the right side of the board, which includes transformers and BNC connectors. There is an optional external LIU (DS3154) that can be used in certain configurations. Located one above and one below of the DS3174 are two FPGAs that, along with headers, provide access to the overhead signals. The microprocessor is on the left top of the board, clock distribution is in the left center, and system interface is at the left bottom. General-purpose LEDs, which are driven by configurable outputs, are located at the top of the board. In the upper-left corner are banana jacks for ground, 5V (regulated to provide board V_{DD}), and a separate DS3174 V_{DD} (useful for DS3174 I_{DD} measurements). There are connectors provided for the serial interface to the microprocessor and the JTAG chain. The board also contains DS3, E3, and STS-1 oscillators and the necessary jumpers to configure both the DS3174 and the DS3154 clocking.

Figure 1. Board Floor Plan



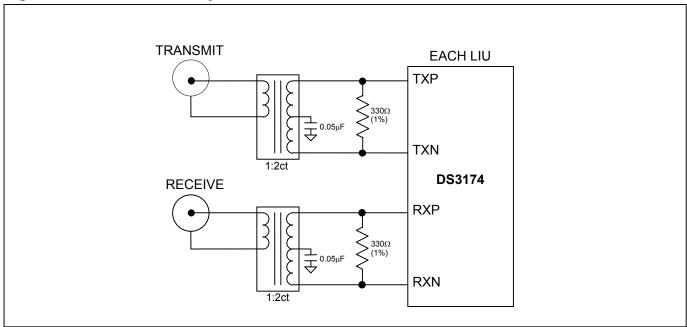
CLOCK JUMPERS

Jumper JMP16 (middle left of board) selects the clock source (external BNC or on-board oscillator) for both CLKA and the system clocks on the DS3174. Jumpers JMP17, JMP18, and JMP23 select the source of the clocks to the external LIU (DS3154), which can be on-board oscillators or a CLAD output of the DS3174. Jumpers JMP24, JMP25, and JMP26 select the specific CLAD output to be connected to the LIU clock inputs on the DS3154.

LINE-SIDE CONNECTIONS

The DS3174DK implements the transmit (Tx) and receive (Rx) line interface networks recommended in the DS3174 data sheet and shown in <u>Figure 2</u>. The BNC connectors for LIU1 are labeled TX1 and RX1. The BNC connectors for LIU2 are labeled TX2 and RX2. The BNC connectors for LIU3 are labeled TX3 and RX3. The BNC connectors for LIU4 are labeled TX4 and RX4.

Figure 2. Line-Side Circuitry



SYSTEM CONNECTOR

The system interface connectors J2 and J3 are not used on the DS3174DK version of this board.

MICROCONTROLLER

The DS87C520 microcontroller has factory-installed firmware in on-chip nonvolatile memory. This firmware translates memory access requests from the RS-232 serial port into register accesses on the DS3174. When the microcontroller starts up it turns on DS1, a green LED, to indicate that the controller is working correctly.

POWER-SUPPLY CONNECTORS

Connect a 5.0V power supply with a current rating of at least 1 amp across the red J1 and black J5 (GND) banana jacks for normal operation. Banana jack J4 accommodates DS3174 IDD measurements. This is accomplished by disconnecting the DS3174 VDD connections from the board VDD by removing jumpers 19, 20, 21, and 22. Diode D1 provides protection against power connection reversal. The LED DS21 provides indications that a 5V supply is connected properly. The 5V supply is regulated to supply proper voltages to various circuits on the board.

CONNECTING TO A COMPUTER

Connect a standard DB-9 serial cable between the serial port on the DS3174DK and an available serial port on the host computer. The host computer must be a Windows®-based PC. Be sure the cable is a standard straight-through cable rather than a null-modem cable. Null-modem cables prevent proper operation.

INSTALLING AND RUNNING THE SOFTWARE

ChipView is a general-purpose program that supports a number of Dallas Semiconductor demo kits. To install the ChipView software, run SETUP.EXE from the disk included in the DS3174DK box or from the zip file downloadable on our website at www.maxim-ic.com/DS3174DK.

After installation, run the ChipView program with the DS3174DK board powered up and connected to the PC. If the default installation options were used, one easy way to run ChipView is to click the **Start** button on the Windows toolbar and select Programs—ChipView—ChipView. In the opening screen, click the **Register View** button. (The **Demo** and **Terminal** buttons are not supported for the DS3174DK.) Select the correct serial port in the *Port Selection* dialog box, then click OK.

Next, the *Definition File Assignment* window appears. This window has subwindows to select definition files for up to four separate boards on other Dallas evaluation platforms. Because ChipView is communicating with the DS3174DK, only one subwindow is active. In the active subwindow, select the **DS3174.DEF** definition file from the list shown, or browse to find it in another directory. Press the **Continue** button.

After selecting the definition file, the main part of the ChipView window displays the DS3174's register map (described in the DS3174 data sheet). To select a register, click on it in the register map. When a register is selected, the full name of the register and its bit map are displayed at the bottom of the ChipView window. Bits that are logic 0 are displayed in white, while bits that are logic 1 are displayed in green.

The ChipView software supports the following actions:

- Toggle a bit. Select the register in the register map and then click the bit in the bit map.
- Write a register. Select the register, click the Write button, and enter the value to be written.
- Write all registers. Click the Write All button and enter the value to be written.
- Read a register. Select the register in the register map and click the Read button.
- Read all registers. Click the Read All button.

Windows is a registered trademark of Microsoft Corp.

BASIC DS3174DK CONFIGURATION

The following example DS3 configuration provides a quick start to using the DS3174DK. The DS3174 and the DS3174DK can be configured in many other ways. To set up other configurations, refer to Section 9 of the DS3174 data sheet and other sections of this data sheet.

The following configuration supports port 1 only. The same directions apply for additional ports using the DEF files that support the specific port.

- Connect 5V between J1 and J5 and verify that jumpers 19 through 22 are installed. Verify LEDs DS1 and DS21 are on. Connect 75Ω coaxial cables to connectors J6 (Rx) and J7 (Tx). Verify J3 and J4 jumpers are set to the 84 position.
- Connect the serial port of a computer to J21. Run the ChipView application and load the definition file named DS3174.DEF provided with the kit.

The following registers in the DS3174 need to be configured. For ChipView-specific help, review the ChipView manual.

Select "DS3174.def slot_0" from the "DEF File Selection" Menu

Click Read All

Put DS3174 in known condition with all registers set to their default value by initiating a Global Reset

SET GCR1L.RST
CLEAR GCR1L.RST
CLEAR GCR1L.RSTDP

clear data path resets

Note: To configure all 4 ports simultaneously, set GCR1U.GWRM.

SET GCR1U.SIW[1:0] = 01 16 bit system interface

SET GCR1U.SIM[1:0] = 11 POS PHY L3

Note: UTOPIA L2 is the default setting: GCR1U.SIM[1:0] = 00

Configure internal CLAD

Note: The following CLAD configuration requires a DS3 clock applied to CLKA (CLKB and CLKC are driven low).

See CLAD table in DS317x data sheet for other configurations

CLEAR GCR2L.CLAD3
SET GCR2L.CLAD2
CLEAR GCR2L.CLAD1
CLEAR GCR2L.CLAD0

Select "ports.def slot 0" from the "DEF File Selection" Menu

Click Read All

CLEAR	PCR1L.RSTDP	normal operation
CLEAR	PCR1L.PD	
SET	PCR1U.PAIS2	disable payload AIS
SET	PCR1U.PAIS1	
SET	PCR1U.PAIS0	
SET	PCR1U.LAIS1	disable line AIS
SET	PCR1II LAISO	

Configure the Framer and LIU

For DS3 C-bit format (default mode)

CLEAR	PCR2L.FM5
CLEAR	PCR2L.FM4
CLEAR	PCR2L.FM3
CLEAR	PCR2L.FM2
CLEAR	PCR2L.FM1
CLEAR	PCR2L.FM0

SET	PCR2U.LM0	LIU on, No JA
SET	PCR2U.LM1	JA on in RX path

PC BOARD LAYOUT RECOMMENDATIONS

Standard high-speed layout guidelines should be observed when designing a PC board to support the DS3174. The following guidelines help to provide stable supply voltages and signal integrity between devices. The DS3174 should have a low-impedance power-supply path that is accomplished with plane layers and an appropriate decoupling scheme. Decoupling capacitors should be connected directly to the planes with minimal trace length. Surface-mount ceramic capacitors should be used with one $0.1\mu F$ per power pin to provide adequate decoupling. Bulk capacitors of the higher capacitance tantalum type should be used near the power-supply connections to provide low-frequency decoupling. All high-speed connections to the DS3174 should be designed with controlled impedance and proper terminations to prevent reflections. The differential connections to the primary or system side of the transformer should be short traces from the DS3174 run together with respect to differential pairs. The connections on the secondary or network side of the transformers should be 75 Ω controlled impedance traces.

DS3174 INFORMATION

The DS3174 Quick View page on our website has the latest DS3174 data sheet, application notes, and downloads. Go to www.maxim-ic.com/DS3174.

DS3174DK INFORMATION

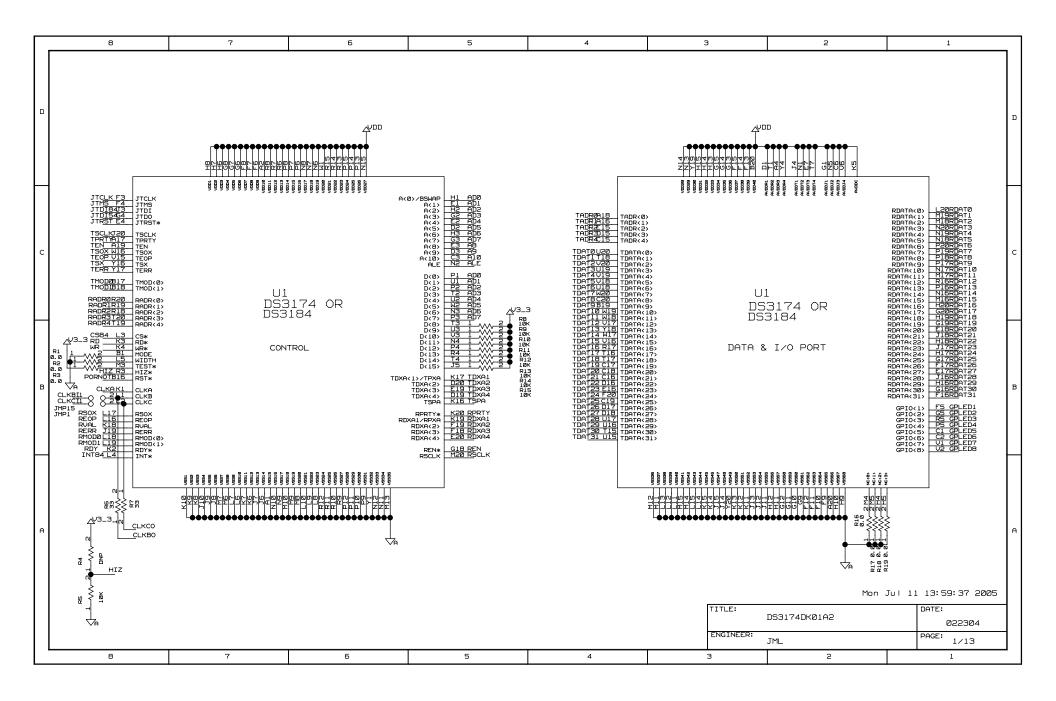
The DS3174DK Quick View page on our website has the latest DS3174DK data sheet, ChipView software updates, and downloads. Go to www.maxim-ic.com/DS3174DK.

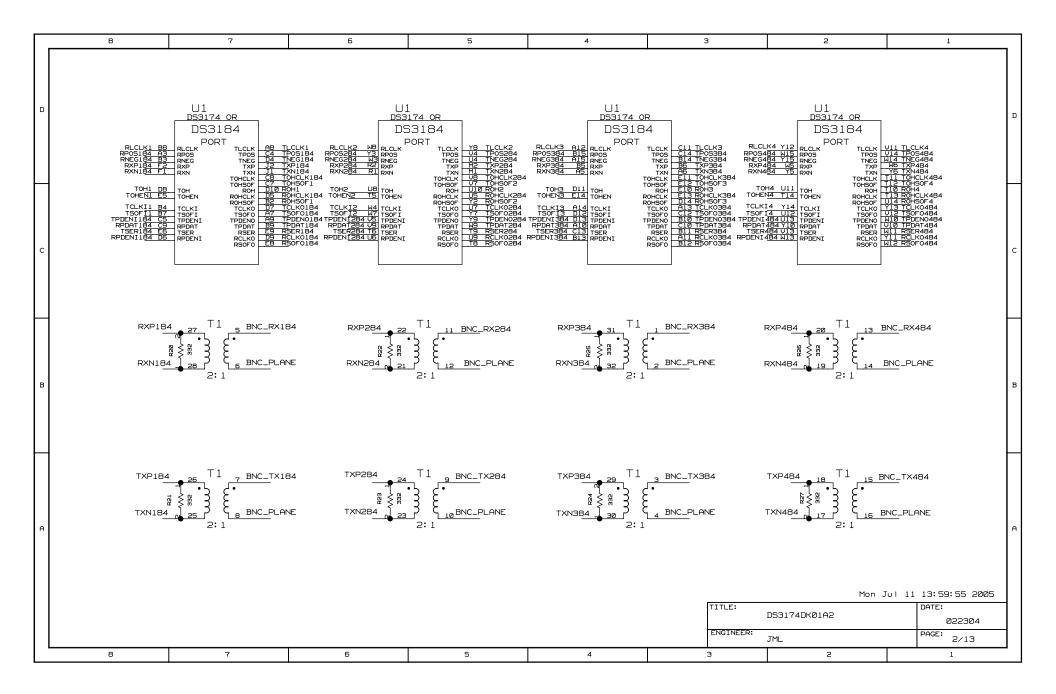
TECHNICAL SUPPORT

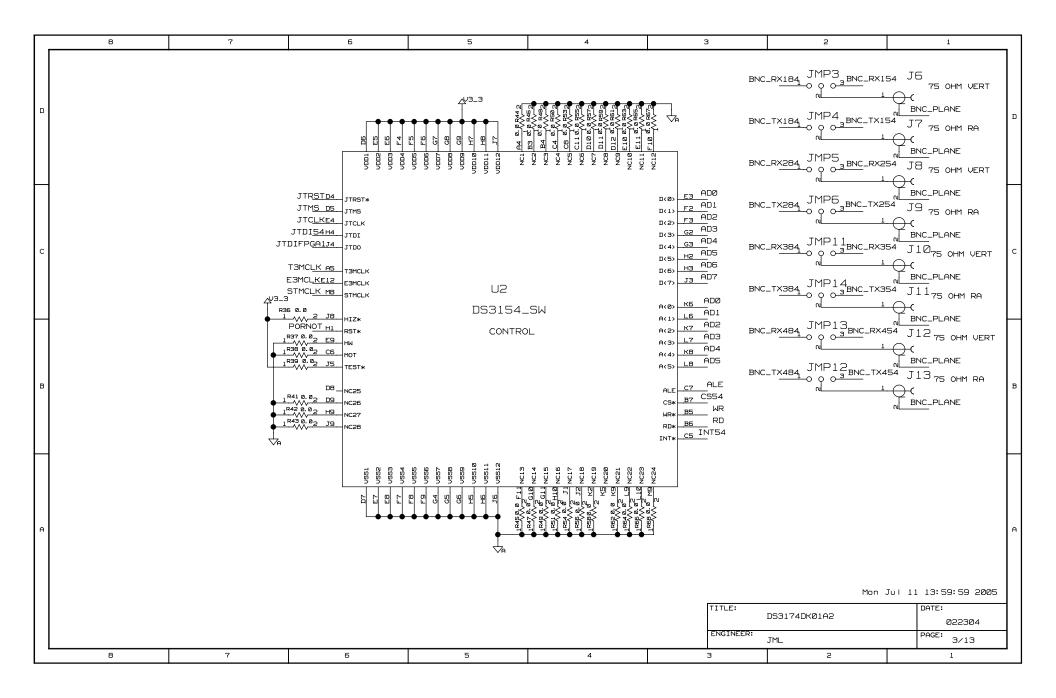
For additional technical support, please email your questions to telecom.support@dalsemi.com.

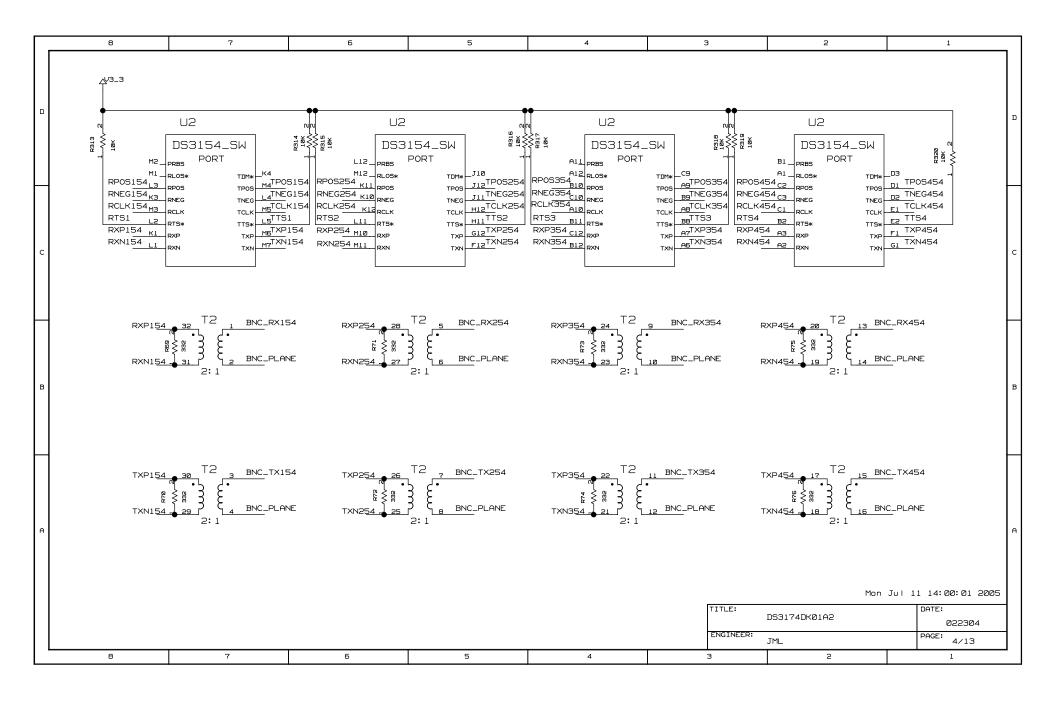
SCHEMATICS

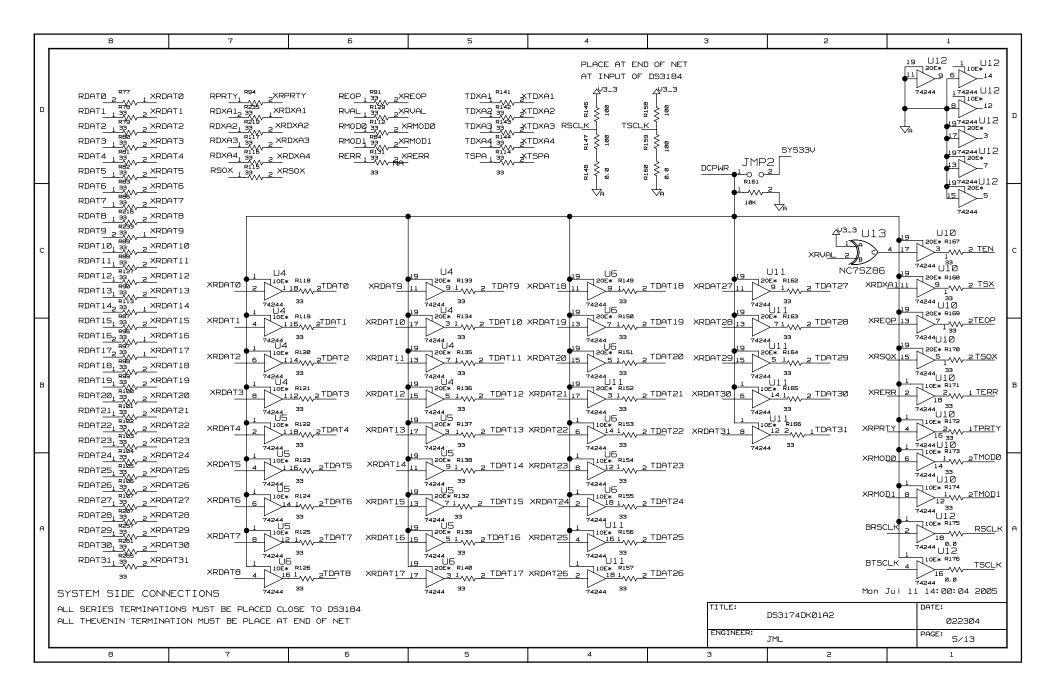
The following 13 pages provide the schematic diagram of the DS3174DK.

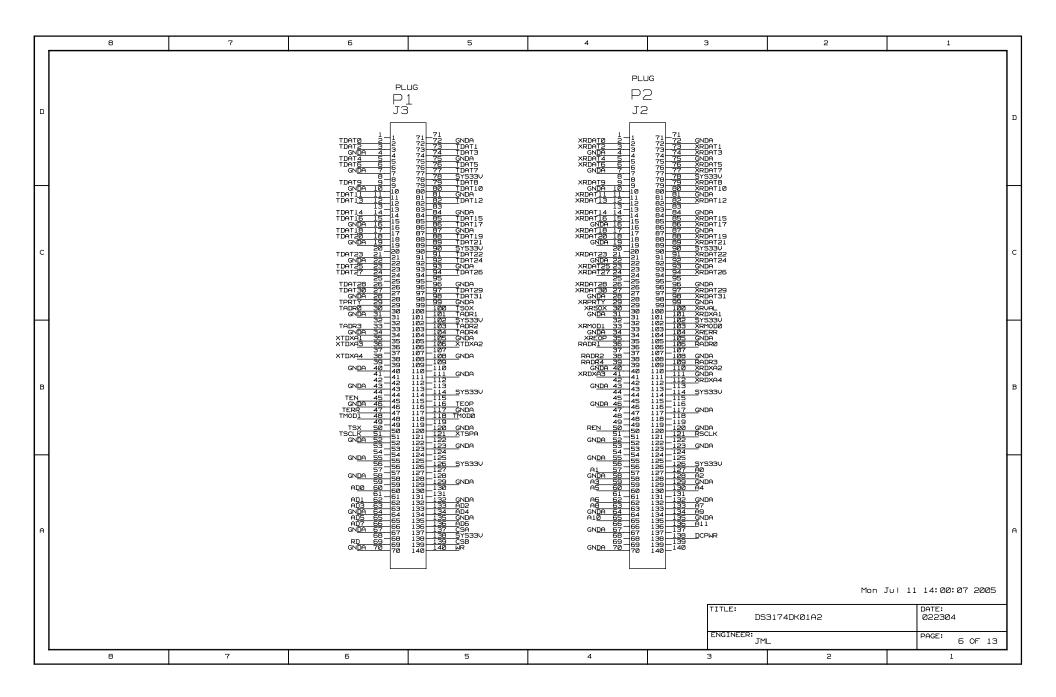




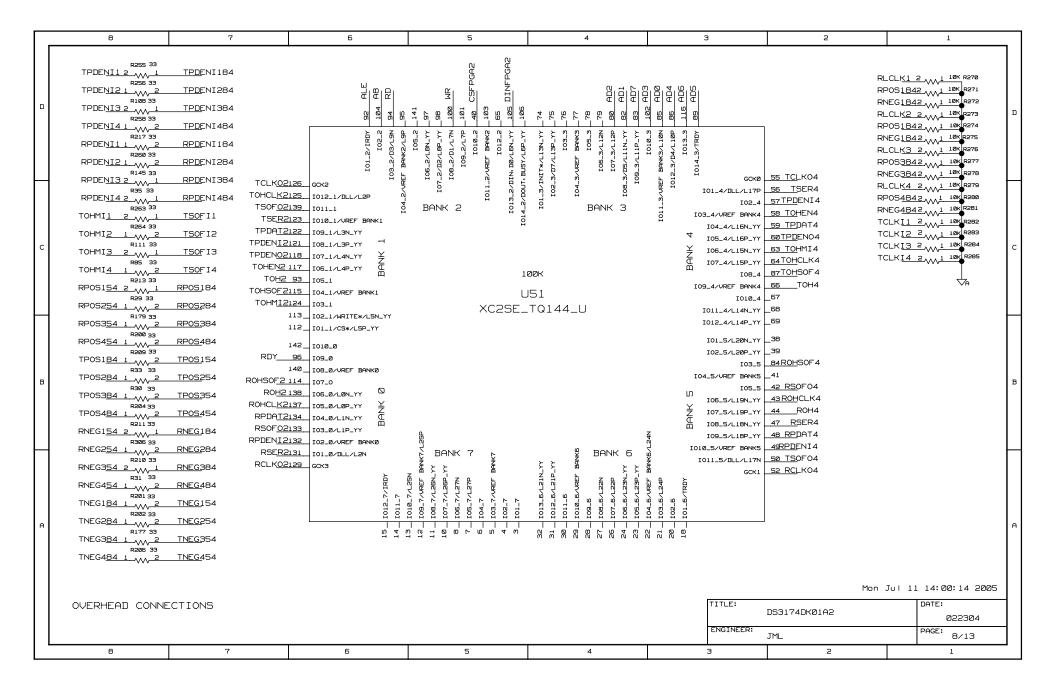


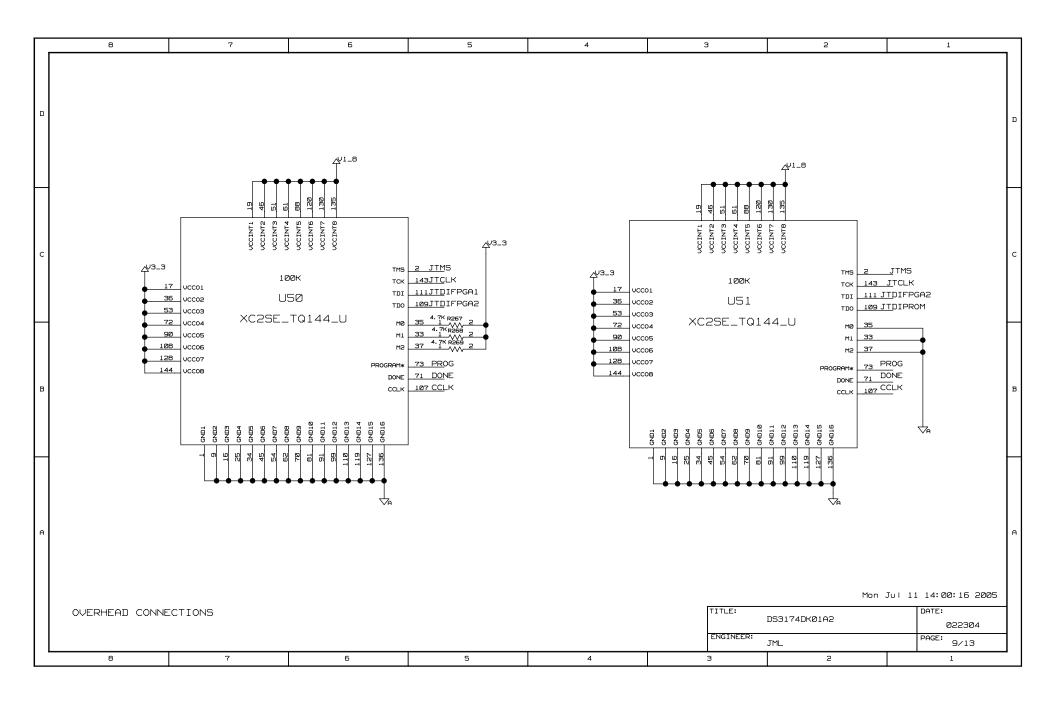


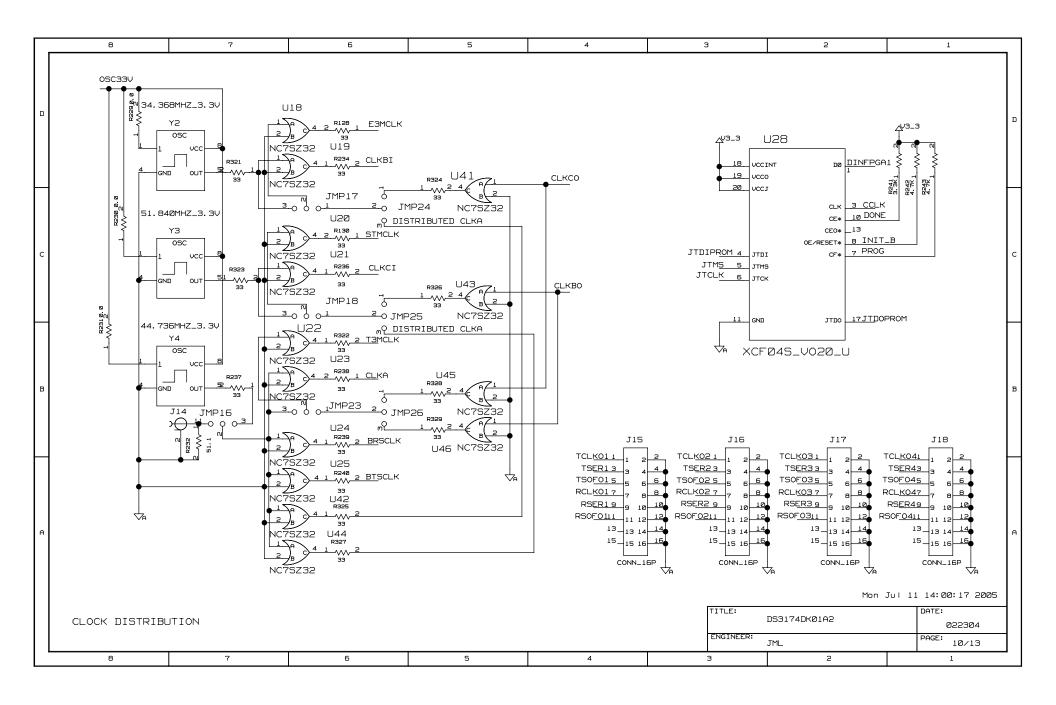


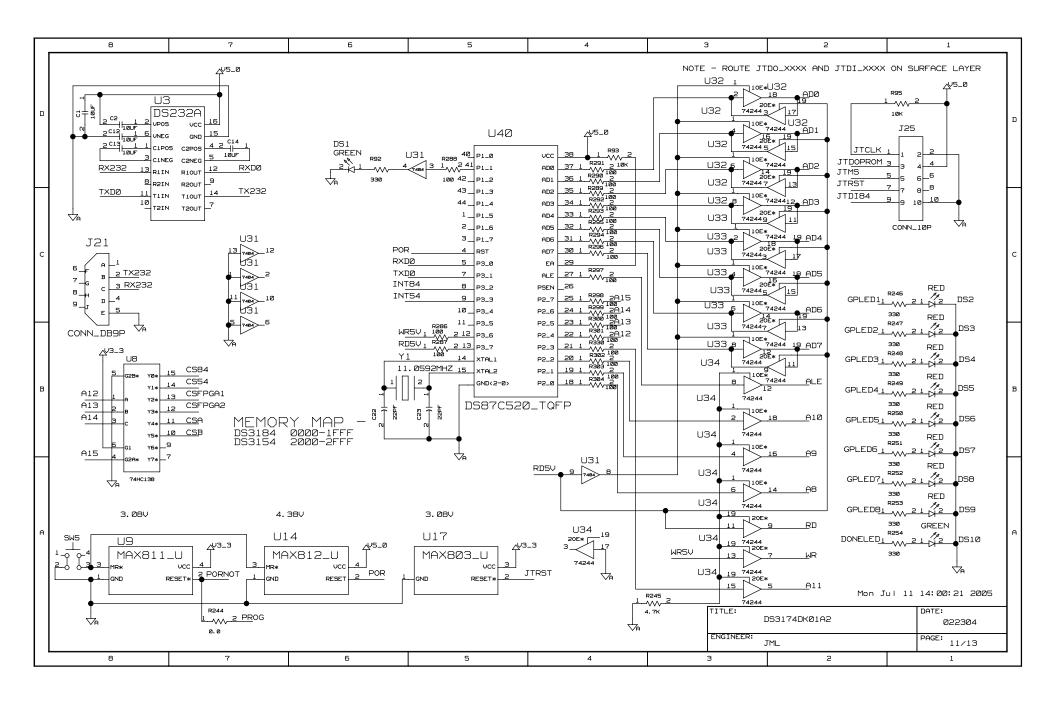


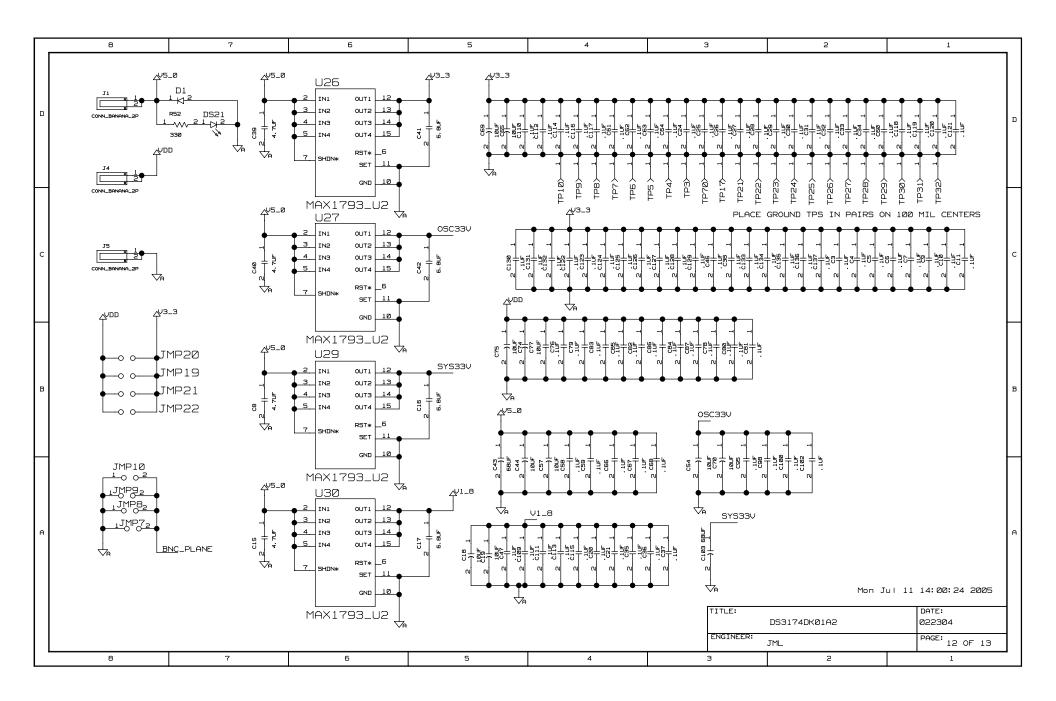
	8	7	6	5	4	3	2	1
ם	RCLK2 <u>54 1 W 2</u> TCLK2 <u>54 1 W 2</u> TCLK2 <u>54 33 R3</u> 08	RLCLK1 2 TLCLK1 RLCLK2 2 TLCLK2	7 S S S S S S S S S S S S S S S S S S S	7 97 67 98 66 N 100 WR 101 100 WR 101 100 WR 2 104 CSF PGA 1 2 104 DONE LED 4 105 DINFPGG 1	7 74 A5 7 142 A4 142 A4 142 A4 142 A4 142 A6 152 A6 163 A6 164		RSOFC RSOFC RSOFC	R259 33 0184 1
	RCLK354 1 33 8397 TCLK354 33 8397 RCLK454 1 83 23 TCLK454 1 82 33 828 TCLK454 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	RLCLK3 1 TLCLK3 RLCLK4 TCLK03 2 TLCLK4 TOHCLK3		105.2 D 105.2 ABN.YY D 105.2 ABN.Z 1011.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z 1013.2 ABN.Z	TOL_3/INIT*/LI3N-YY TOZ_3/D7/LI3P-YY TOZ_3/D7/LI3P-YY TOZ_3/UREF BRNC3 TOZ_3/LI2N-YY TOZ_3/LI2N-YY TOZ_3/LI2N-YY TOZ_3/LI2N-YY	101_4/DLL/L17P	TSOF0 TSOF0 <u>55 TCL</u> K01 <u>56 TS</u> ER1 TSOF0	R199 33 0284 1
С	TCLKO <u>184 1 </u>	TSOFQ3 TSER3 TSER3 TCLK01 TPDENI3 TCLK02 TPDENQ3 TOHEN3	102 1011.1 5 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1			Z U 107_4/L15P_YY U	58 TOHENT 59 TPDAT1 60TPDENO1 63 TOHMI1 64TOHCLK1 TOHCL	K184
	TCLK0384 1	TCLK03 TOH3 TCLK04 TOH50F3 RCLK01 TOHMI3 RCLK02 RCLK03	1114 105.1 115 104.1/UREF BANK1 103.1 113 102.1/WRITE*/LSN_YY 112 101.1/CS*/LSP_YY	L	øøк J50 .TQ144_U	I012_4/L14P_YY		K184
В	RSER284 1	RCLK04 RDY	64 109_0 140 108_0/UREF BANK0 95 107_0 138 106_0/L0N_YY \(\) \			103_5	42 RS0F01 RPDAT 43R0HCLK1 RPDAT 44 R0H1	R198 33 2 1
	RSER484 1 W 2 R192 33 RSER484 1 W 2 R193 33 TSER1 2 W 1 R194 33 TSER2 1 W 2 R195 33 TSER3 1 W 2	RSER4 RSOFQ3 RPDENI3 TSER184 RSER3 TSER284 TSER284 TSER384	133	1.77.28N 7.7.VREF BANK7.7.28P 7.7.L26N-YY B 7.7.L26P-YY B 7.7.L27P J 7.7.L27P	3-5/121P-YY 1-5 5-6/121P-YY 1-5 5-6/122N 5-6/122N 5-6/123N 7-7 5-6/123N-YY 5-6/123N-YY 5-6/123N-YY 5-6/123N-YY 5-6/123N-YY 5-6/123N-YY 5-6/123N-YY		48 RPDAT1 TPDAT 49RPDENI1 50 TS0F01 TPDAT 52 RCLK01 TPDAT	184 1
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040885 - A1 - ADDED MISSING SIGNAL NAMES ON PAGE 12 & CLEANED-UP TEXT ON VARIOUS PAGES. 070705 - A2 - ADDED VDD CONNECTION TO TIS/RTS NET FIXED ALE SHORT ACROSS U34 CHANGED R32 VALUE TO 330 OHMS CHANGED R32 VALUE TO 330 OHMS CHANGED R145 AND R167 FROM DNP TO 0 CHANGED R145 R0 R147 R0M DNP TO 0 CHANGED R145 R147 R155 R0M DNP TO 100 OHMS CHANGED JNP19 TO JMP25 FROM DNP TO 100 OHMS CHANGED SARE DOCUMENT CHANGES TO MATCH MODIFIED BOARDS WITH SCHEMATIC								
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